KYOCERA

TECHNICAL REPORT

Functional materials
CT285
Die Attach Paste

1.Introduction

Die Attach Paste “CT285“ is epoxy resin based and solvent free Type paste.
The highest thermal conductivity (25W/mK)
Good reflow performance due to lower moisture absorption resin system.
CT285 is effectively used for power IC, transistor..

2.Features

1) Good workability for dispensing due to solvent free and one liquid type paste.
2) Highest thermal conductivity(25W/mK)
3) Bleed less.

3. General Property

Properties		Unit	Typical Value	Test Method
Appearance		-	Silver Filled Paste	Visual
Viscosity at 25C		Pa･s	100	E-Type Viscometer 0.5rpm (3° cone)
Thixotropic Index		-	6.0	0.5rpm/5.0rpm
Non Volatile		wt%	92.0	180C×2hr
Silver Content		wt%	87.5	600C×3hr
Die shear strength	25C 300C	Kgf	3.5 2.8	Frame : Cu/PPF Chip Size : 2x2mm
Volume Resistivity		Ohm･cm	8×10^{-6}	Cure : 200Cx90min. Measurement: Room Temp.
Glass Transition Temperature		C	160	TMA
Modules（25C）	25C	GPa	16.5	DMA
	260C		7.8	
CTE	Alpha1	Ppm	40	TMA
	Alpha2		125	
Ionic Impurity	Na Cl	ppm	6 1	Atomic Absorption Ionchromatography
Thermal Conductivity		W/m K	25	Laser Flash

4. Standard Curing Condition

[1st Step] 150C x 30min + [2nd Step] 200C x 90min. (Keeping time) in Oven

5. Remarks

Storage condition is -30 to -15C

KYOCERA Chemical Corporation

SALES DIVISION OVERSEAS SALES Dept. Tel; +81-(0)-48-225-6915 Fax; +81-(0)-48-225-6927
5-14-25 RYOKE, KAWAGUCHI, SAITAMA 332-8533, JAPAN